JOCT101Xh-L4 Series

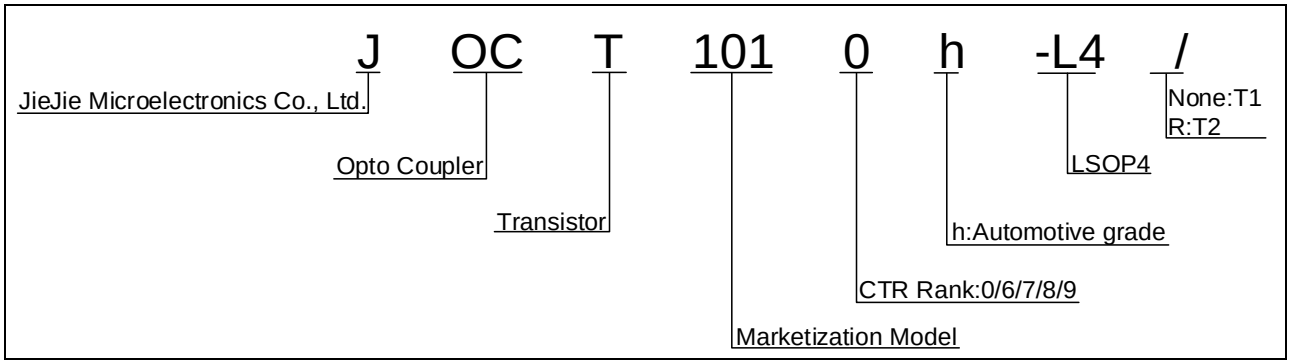
Junction Temperature	T_j	135	
Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

: 100μs pulse, 100Hz frequency
: AC for 1minute, R.H.=40~60%

(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
	Terminal Capacitance	C_t	V=0,f=1MHz	-	30	250	pF
	Collector-Emitter dark current	I_{CEO}	V_{CE}=20V, I_F=0	-	-	50	nA
Output	Collector-Emitter breakdown voltage	BV_{CEO}	I_C=0.1mA I_F=0	80			V
	Emitter-Collector breakdown voltage	BV_{ECO}	I_E=0.1mA I_F=0	7	-	-	V
	Current transfer ratio	CTR	I_F=5mA V_{CE}=5V	80	-	600	%

Transfer
Characteristics



None/R	3000 Units/Reel

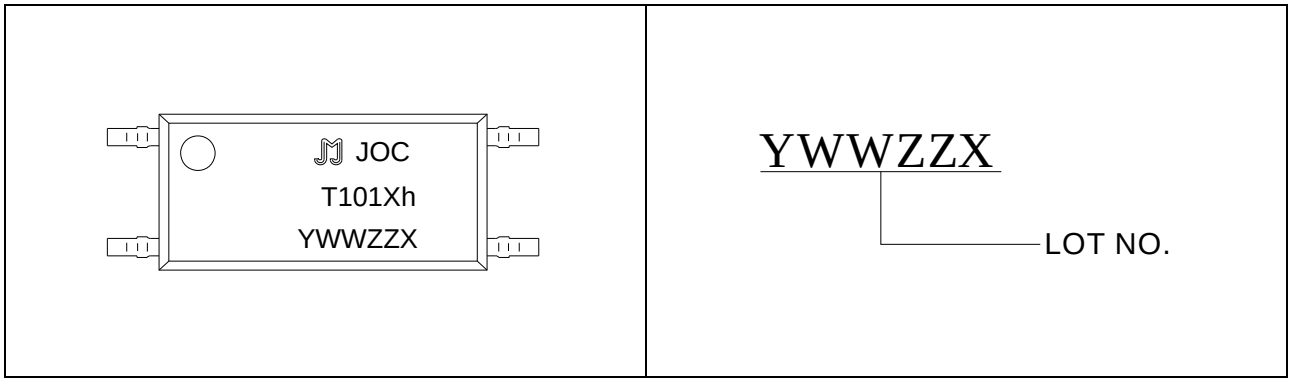


FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

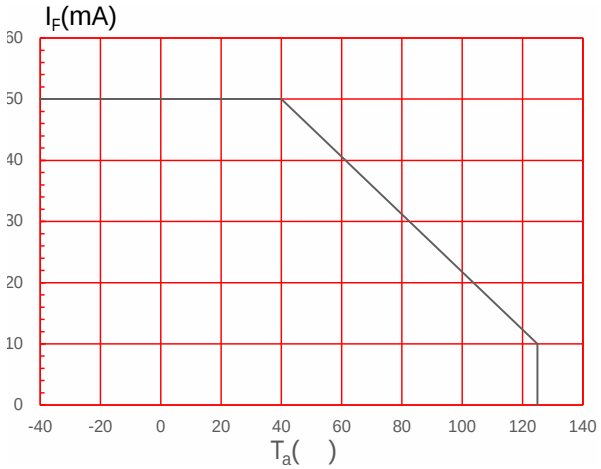


FIG.2: Collector Power Dissiption vs. Ambient Temperature

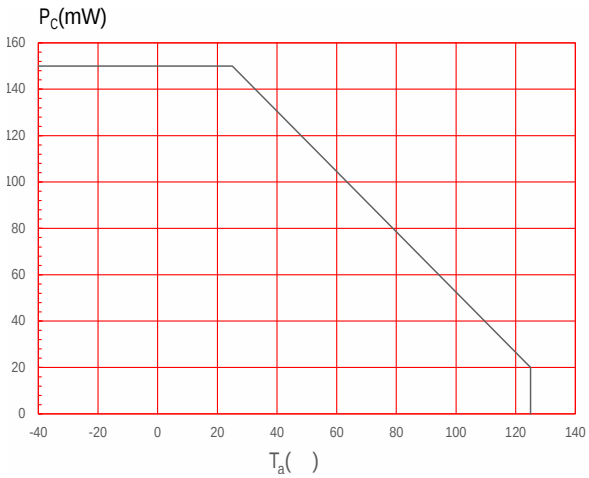


FIG.3: Forward Current vs. Forward Voltage

FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

FIG.11: Test Circuits of Response Time

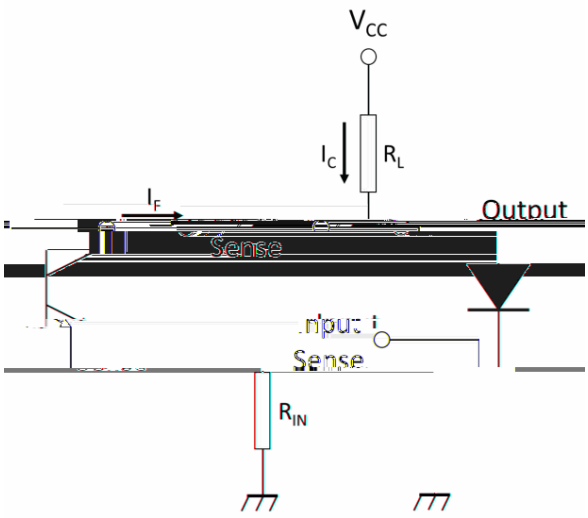


FIG.12: Curves of Response Time

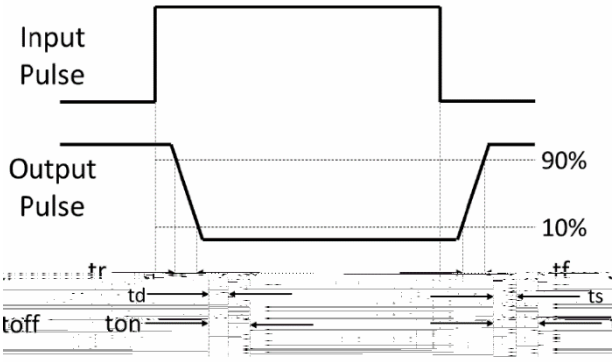
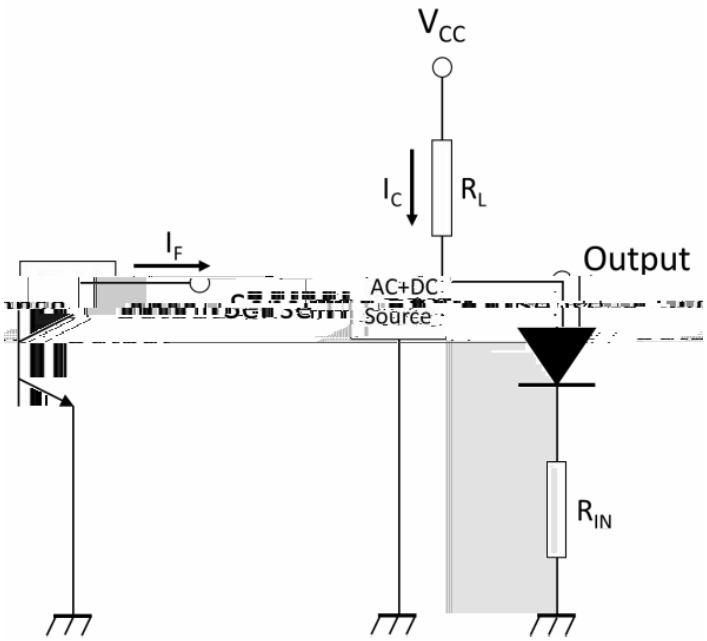
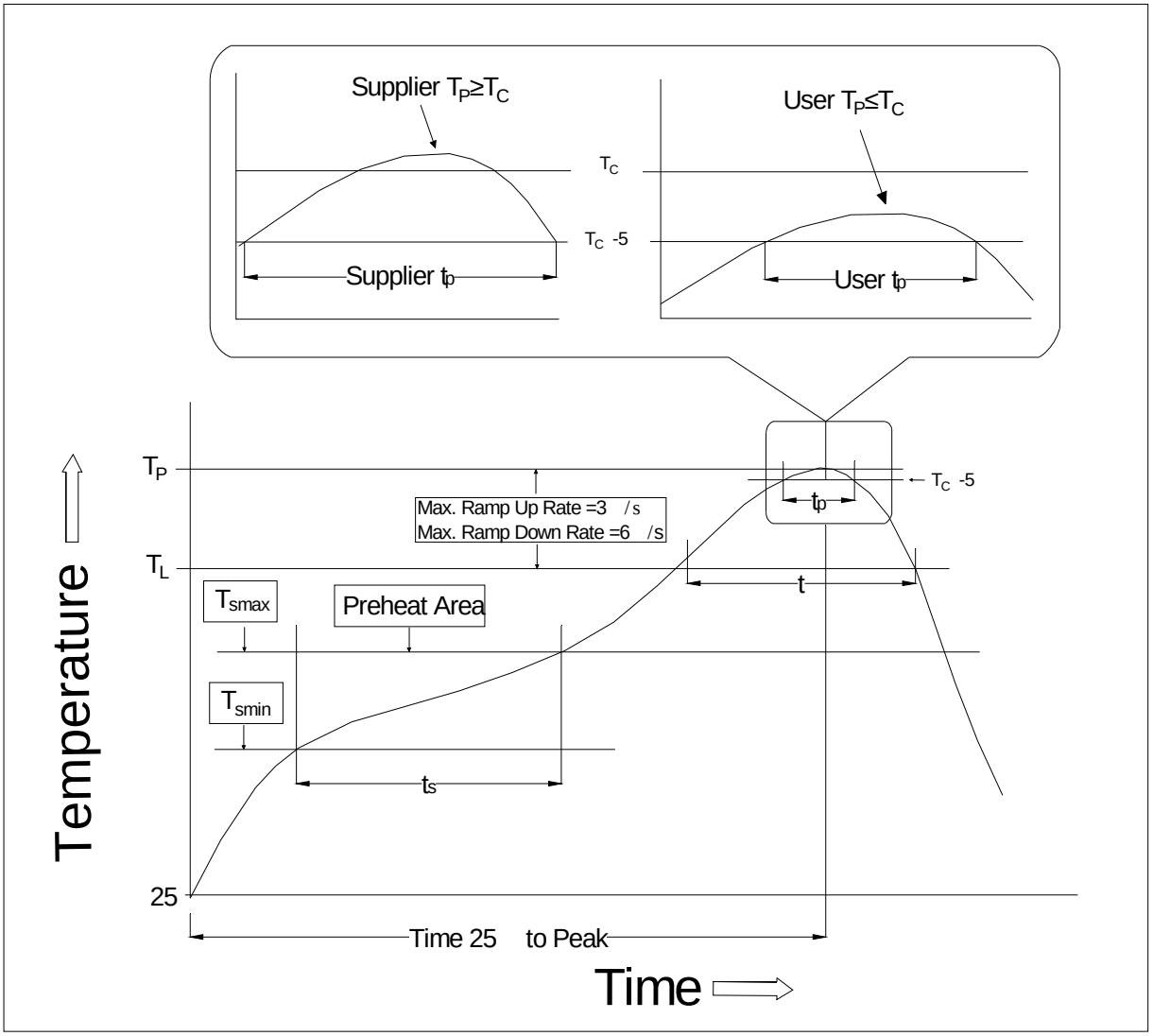


FIG.13: Test Circuits of Frequency Response



	Dimensions	
Ref.	Millimeters	Inches



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6 /second max.	6 /second max.
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1